

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	TETSUMASA ITO	07/25/2014
<b>RECEIVING PARTY DATA</b>		
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<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	14376552
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<b>ATTORNEY DOCKET NUMBER:</b>	SIP133	
<b>NAME OF SUBMITTER:</b>	STEVEN J. GROSSMAN, PH.D.	
<b>SIGNATURE:</b>	/Steven J. Grossman, Ph.D./	
<b>DATE SIGNED:</b>	08/06/2014	
<b>Total Attachments: 3</b>		
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## ASSIGNMENT OF UNITED STATES PATENT APPLICATION

WHEREAS, I/We, **Tetsumasa ITO** made certain new and useful inventions and improvements for which I/We filed, or will be filing, an application for Letters Patent of the United States, identified as U.S. patent application serial number 14/376,552 filed on August 4, 2014, which application is entitled:

### **THIN SECTION FABRICATION APPARATUS AND METHOD OF FABRICATING THIN SECTION**

AND, WHEREAS, I/We hereby authorize and request an attorney associated with Customer Number 32047 to insert on the designated lines above, the filing date and application number of said application when known;

AND, WHEREAS, **SAKURA FINETEK JAPAN CO., LTD.**, corporation organized and existing under and by virtue of the laws of **Japan**, and having an office and place of business at **1-9, Nihonbashi-Honcho 3-chome, Chuo-ku, Tokyo 103-0023 Japan**, (hereinafter "Assignee"), is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefore;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, I/We have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted there from, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed under the Patent Cooperation Treaty, in any regional patent offices and in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted there

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from; and I/We do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letter Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, I/We do hereby agree that I/We and my/our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to me/us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be;

AND, furthermore, I/We covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me/us and that full right to convey the same as herein expressed is possessed by me/us.

AND, as a named inventor, I hereby declare that:

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application, including the claims, and I am aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in 37 C.F.R. § 1.56.

11P01020  
OSP 33060  
US 7643 7A (3/3)

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 25th. day of July, 2014.

Tetsumasa ITO  
Tetsumasa ITO